

SSC8L420GT8

N-Channel Enhancement Mode MOSFET

> Features

V _{DS}	V _{GS}	R _{DS(ON)} Typ.	l _D
40V	±20V	2.6mΩ@10V	122A
		3.3mΩ@4V5	1227

Description

This device is N-Channel enhancement MOSFET.

Uses SGT technology and design to provide excellent

RDSON with low gate charge. This device is suitable
for use in DC-DC conversion, power switch and
charging circuit.

100% UIS + ΔVDS + Rg Tested!

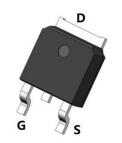
Applications

- DC/DC converters
- Power supplies
- Motor Drive Control
- Synchronous rectification

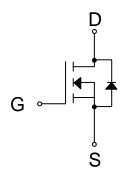
Ordering Information

Device	Package	Shipping	
SSC8L420GT8	TO-252-2L	2500/Reel	

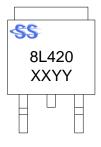
Pin Configuration



TO-252-2L (Top View)



Pin Configuration



Marking

(XXYY: Internal Traceability Code)



Absolute Maximum Ratings (T_A=25[°]C unless otherwise noted)

Symbol	Parameter	Ratings	Unit	
V _{DSS}	Drain-to-Source Voltage		40	V
V _{GSS}	Gate-to-Source Volta	Gate-to-Source Voltage		V
	Continuous Drain Current ^d	T _C =25℃	122	^
l _D		T _C =100℃	68	- A
	Continuous Drain Current ^a	T _A =25℃	21	Δ.
IDSM		T _A =70°C	15	- A
Ірм	Pulsed Drain Curren	Pulsed Drain Current b		Α
5	Power Dissipation °	Tc=25℃	83	34/
P _D		T _C =100℃	33	W
	Power Dissipation ^a	T _A =25℃	2.5	34/
P _{DSM}		T _A =70°C	1.6	W
las	Avalanche Current ^b L=0.5mH Single Pulse		32	Α
Eas	Avalanche Energy b L=0.5mH Single Pulse		256	mJ
TJ	Operation junction temperature		-55~150	°C
T _{STG}	Storage temperature ra	-55~150	\mathbb{C}	

➤ Thermal Resistance Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Max	Unit
Reja	Junction-to-Ambient Thermal Resistance a	36	50	°C/W
$R_{ heta JC}$	Junction-to-Case Thermal Resistance	1.1	1.5	CIVV

Note:

- a. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with T_A=25°C. The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.

SSC-V1.0 www.sscsemi.com Analog Future



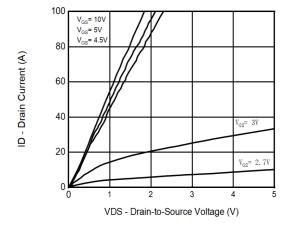


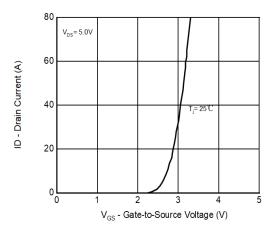
\succ Electrical Characteristics (T_A=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	40			V
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250uA$	1	1.5	2.0	V
D	Drain-Source On-Resistance	V _{GS} = 10V, I _D = 20A		2.6	3.5	mΩ
R _{DS(on)}		V _{GS} = 4.5V, I _D = 10A		3.3	4.5	
IDSS	Zero Gate Voltage Drain Current	V _{DS} = 40V, V _{GS} = 0V			1	μA
Igss	Gate-Source Leak Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			±200	nA
V _{SD}	Forward Voltage	V _{GS} = 0V, I _S = 10A		0.75	1.3	V
R _G	Gate Resistance	V _{DS} = 0V, f = 1MHz		1.3		Ω
Ciss	Input Capacitance	\\ - 20\\ \\ - 0\\		2825		
Coss	Output Capacitance	$V_{DS} = 20V$, $V_{GS} = 0V$, $f = 1MHz$		670		pF
C _{RSS}	Reverse Transfer Capacitance	I – IIVIMZ		81		
Q _G	Total Gate Charge	V - 40V V - 20V		57		
Q _{GS}	Gate to Source Charge	$V_{GS} = 10V, V_{DS} = 20V,$ $I_{D} = 20A$		7.0		nC
Q _{GD}	Gate to Drain Charge	ID - 20A		12		
T _{D(ON)}	Turn-on Delay Time			8.8		
Tr	Rise Time	V _{GS} = 10V, V _{DS} = 20V,		25		
T _{D(OFF)}	Turn-off Delay Time	$R_L = 1\Omega$, $R_G = 3\Omega$		41		ns
Tf	Fall Time			33		
Trr	Diode Recovery Time	I⊧=20A, di/dt=500A/us		45		ns
Qrr	Diode Recovery Charge	I _F =20A, di/dt=500A/us		98		nC



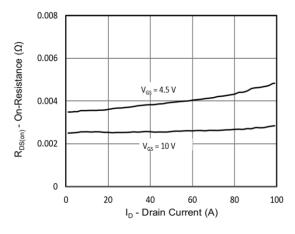
> Typical Performance Characteristics (T_A=25℃ unless otherwise noted)

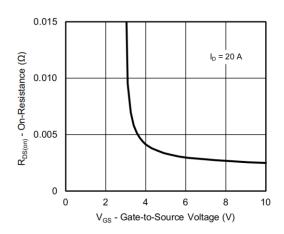




Output Characteristics

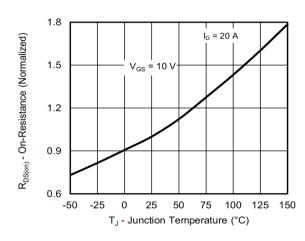
Transfer Characteristics

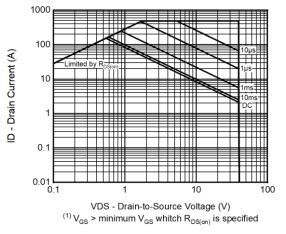




On-Resistance vs. Drain Current

On-Resistance vs. Gate-to-Source Voltage



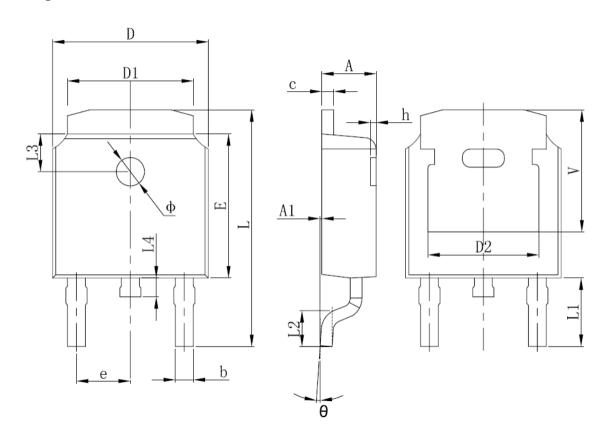


On-Resistance vs. Junction Temperature

Safe Operating Area



Package Information



Package: TO-252-2L

Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	0.900	1.000	0.035	0.039	
A3	0.254REF		0.010	DREF	
D	4.944	5.096	0.195	0.201	
E	5.974	6.126	0.235	0.241	
D1	3.910	4.110	0.154	0.162	
E1	3.375	3.575	0.133	0.141	
D2	4.824	4.976	0.190	0.196	
E2	5.674	5.826	0.223	0.229	
k	1.190	1.390	0.047	0.055	
b	0.350	0.450	0.014	0.018	
е	1.270TYP		0.050	OTYP	
L	0.559	0.711	0.022	0.028	
L1	0.424	0.576	0.017	0.023	
Н	0.574	0.726	0.023	0.029	
θ	10°	12°	10°	12°	



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